

# **Automotive** Dual N-Channel 60 V (D-S) 175 °C MOSFET

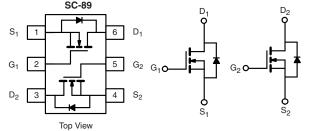
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	1.4			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	2.0			
I <sub>D</sub> (A)	0.3			
Configuration	Dual			

## **FEATURES**

- Halogen-free According to IEC 61249-2-21 **Definition**
- TrenchFET® Power MOSFET
- Compliant to RoHS Directive 2002/95/EC
- AEC-Q101 Qualified<sup>c</sup>







Marking Code: E

N-Channel MOSFET N-Channel MOSFET

ORDERING INFORMATION	
Package	SC-89
Lead (Pb)-free and Halogen-free	SQ1026X-T1-GE3

ABSOLUTE MAXIMUM RATING	GS (T <sub>A</sub> = 25 °C, unless	s otherwise noted	(b)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		$V_{DS}$	60	.,	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	0.3	A	
	T <sub>A</sub> = 125 °C		0.2		
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	0.3	A	
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	1.2		
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C	- P <sub>D</sub>	0.300	w	
	T <sub>A</sub> = 125 °C		0.100		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>sta</sub>	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mountb	R <sub>thJA</sub>	500	°C/W	

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- b. When mounted on 1" square PCB (FR-4 material).
- c. Parametric verification ongoing.



PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static	1				L	·		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60	-	-	.,	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1	1.5	2.5	V	
Gate-Source Leakage		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$		-	-	± 1	μΑ	
	I <sub>GSS</sub>	V <sub>DS</sub> =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 1	mA	
Zero Gate Voltage Drain Current		$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V	-	-	1.0		
	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ	
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C	-	-	150		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	V <sub>DS</sub> ≥ 5 V	0.500	-	-	Α	
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 500 mA	-	1.1	1.4	Ω	
		V <sub>GS</sub> = 10 V	$I_D = 500 \text{ mA}, T_J = 125 \text{ °C}$	-	-	2.41		
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 500 mA, T <sub>J</sub> = 175 °C	-	-	3.04		
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 200 mA	-	1.5	2.0		
Forward Transconductanceb	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 200 mA		-	0.200	-	S	
Dynamic <sup>b</sup>	•							
Input Capacitance	C <sub>iss</sub>		/ <sub>GS</sub> = 0 V V <sub>DS</sub> = 25 V, f = 1 MHz	-	21	27	pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	6	8		
Reverse Transfer Capacitance	C <sub>rss</sub>	1		-	4	5		
Total Gate Charge <sup>c</sup>	Qg		V <sub>DS</sub> = 30 V, I <sub>D</sub> = 250 mA	-	1.00	1.5	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V		-	0.16	-		
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	0.24	-		
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>	$V_{DD} = 30 \text{ V, } R_L = 30 \Omega$ $I_D \cong 1 \text{ A, } V_{GEN} = 10 \text{ V, } R_g = 6 \Omega$		-	5	8		
Rise Time	t <sub>r</sub>			-	11	17	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	V <sub>DD</sub>	$V_{DD} = 30 \text{ V}, R_{L} = 30 \Omega$		9	14		
Fall Time	t <sub>f</sub>	$I_D \cong 1 \text{ A, } V_{GEN} = 10 \text{ V, } R_g = 1 \Omega$		-	10	15		
Diode Ratings and Characteristics <sup>b</sup>	•	•						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	1.2	Α	
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 200 mA, V <sub>GS</sub> = 0 V				1.2	V	

#### **Notes**

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

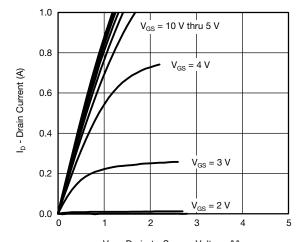
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



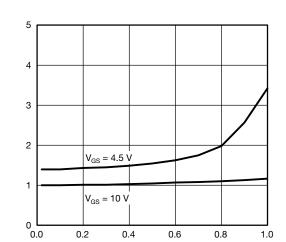


R<sub>DS(on)</sub> - On-Resistance (Ω)

## TYPICAL CHARACTERISTICS (T<sub>C</sub> = 25 °C, unless otherwise noted)

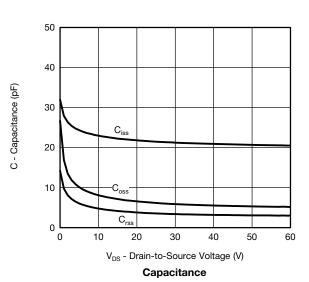


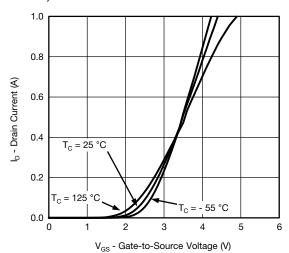
V<sub>DS</sub> - Drain-to-Source Voltage (V) **Output Characteristics** 



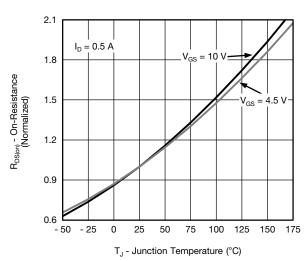
I<sub>D</sub> - Drain Current (A)

On-Resistance vs. Drain Current

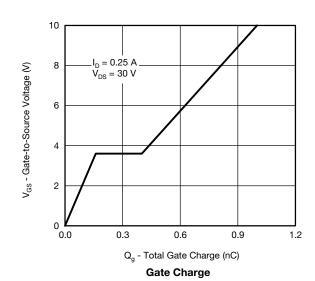




Transfer Characteristics

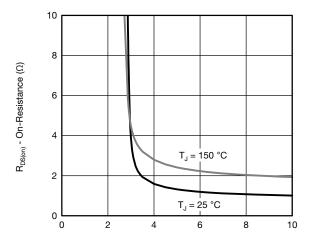


**On-Resistance vs. Junction Temperature** 



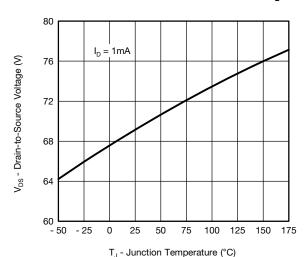


## **TYPICAL CHARACTERISTICS** ( $T_C = 25$ °C, unless otherwise noted)

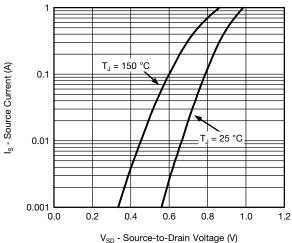


V<sub>GS</sub> - Gate-to-Source Voltage (V)

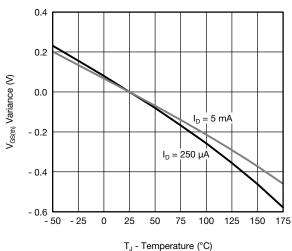
#### On-Resistance vs. Gate-to-Source Voltage



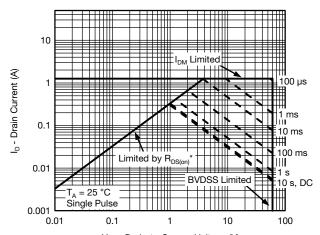
**Drain Source Breakdown vs. Junction Temperature** 



### Source-Drain Diode Forward Voltage



**Threshold Voltage** 

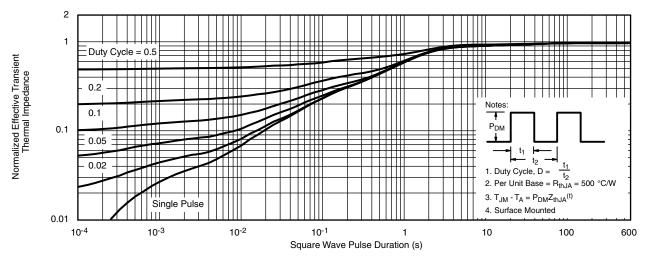


V<sub>DS</sub> - Drain-to-Source Voltage (V) \*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area



### **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

#### Note

The characteristics shown in the the graph Normalized Transient Thermal Impedance Junction to Ambient (25 °C) is given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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